

Announcement of Material Science and Engineering

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Abstract

Meetings International presents the Material Science and Engineering, scheduled on September 23-24, 2022 Osaka, Japan; which will allow the professional to characteristic their exploration of work through introductions and have a probability to select up mastering about the present circumstance of Material Science and Engineering. Major attractions of this event would revolve around keynote presentations, oral presentations and poster presentations. This year we are focusing on the theme "Materials Science And Engineering As A Multidiscipline". Materials Science And Engineering. As A Multidiscipline seems to be the constantly trending subject matter with modern day research technologies. Everyone who explores to strengthen their knowledge and gain extended about advanced technical cleverness is welcome to present/get new ideas. Material Science Conference captivates individuals both from commercial and academic worlds yet establishes a firm link and binds us together with the recent updated accomplishments. We provide a good opportunity by admiring your updated research and also by publishing it in our respective journals. We assure our attendees return to their place with the self-belief to improve their abilities and outfitted with certified approaches to work with us. This meeting will allow the attendees to acquire these new updates and share their experiences with well-recognized speakers globally.

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Biography

Ephraim Suhir is on the faculty of the Portland State University, Portland, OR, USA, Technical University, Vienna, Austria and James Cook University, Queensland, Australia. He is also CEO of a Small Business Innovative Research.

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